

## Press Release BUDATEC – BOSCHMAN TECHNOLOGIES

**Budatec and Boschman join forces in developing manual Ag-sintering equipment under variable atmospheric pressure and various gas composition during the entire heating, sintering and cooling procedure.**

**Berlin (D) /Duiven (NL), November 2th, 2017 – Budatec GmbH, a German based equipment manufacturer for the semiconductor and photovoltaic industry, announced today together with Boschman Technologies BV, a Dutch based high-end packaging equipment manufacturer for the semiconductor industry, that they will co-develop the 2<sup>nd</sup> generation manual-production silver sintering equipment. This collaboration enables Boschman Technologies to extend their in-house developed sintering technology with the extensive know-how from Budatec in vacuum systems and various protective gas environments. The first prototype system is expected in June 2018.**

Alexander Dahlbüdding, CEO of Budatec, said: Budatec has found an international cooperation partner in Boschman to meet the demand for production equipment for assembly and connection technology consisting of soldering and sintering. *'It is intended to meet the customer's wishes to offer small compact production/research systems and high throughput designed soldering/sintering equipment under defined atmospheres. Budatec supports Boschman in the technological issues of vacuum soldering technology and the various protective gas atmospheres.'*

Frank Boschman, CEO of Boschman Technologies, indicates that he sees Budatec as their ideal partner who can support them in their ambition to strengthen and grow their international market position. *'We have found in Budatec a reliable partner with a wealth of knowledge and experience in vacuum soldering technology. Combining their expertise with our inhouse Ag-Sinter press and multiple Ag tooling solutions creates a perfect match to deliver this type of equipment. We strive to cover the complete Ag-Sinter market with equipment solutions and services. From initial first process tests, market samples delivery until Ag-sinter systems for High volume manufacturing.'*

### **About Budatec**

Budatec produces equipment for the semiconductor and photovoltaic industries and is located in Berlin. Their main business areas are thermal systems and electronic manufacturing products. Their focus is on vacuum soldering systems, ranging from small Batch installations to fully automated production systems. Budatec has more than 20 years' experience in this area. The vacuum soldering systems are developed and built at our Berlin site and are distributed worldwide. Budatec is one of the technological market leaders in this segment, especially around the use of hydrogen and plasma gases.

### **About Boschman Technologies**

Boschman Technologies in Duiven Netherlands established in 1987 is a high-end niche player within the semiconductor packaging equipment sector. They provide full production solutions for semiconductor packaging specifically in transfer-molding and silver sintering die-attach. They focus on smartcards, sensors, medical, optical and power devices. Boschman Technologies has developed several unique and patented technologies that provide innovative packaging solutions for complex, advanced and demanding sensors and chips.